

Mechanical standardization of semiconductor devices - Part 6-10: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Dimensions of P-VSON

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

Käesolev Eesti standard EVS-EN 60191-6-10:2004 sisaldab Euroopa standardi EN 60191-6-10:2003 ingliskeelset teksti.

Standard on kinnitatud Eesti Standardikeskuse 25.05.2004 käskkirjaga ja jõustub sellekohase teate avaldamisel EVS Teatajas.

Euroopa standardimisorganisatsioonide poolt rahvuslikele liikmetele Euroopa standardi teksti kättesaadavaks tegemise kuupäev on 05.12.2003.

Standard on kättesaadav Eesti standardiorganisatsioonist.

This Estonian standard EVS-EN 60191-6-10:2004 consists of the English text of the European standard EN 60191-6-10:2003.

This standard is ratified with the order of Estonian Centre for Standardisation dated 25.05.2004 and is endorsed with the notification published in the official bulletin of the Estonian national standardisation organisation.

Date of Availability of the European standard text 05.12.2003.

The standard is available from Estonian standardisation organisation.

ICS 31.080.01

Võtmesõnad:

Standardite reprodutseerimis- ja levitamiseõigus kuulub Eesti Standardikeskusele

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Mechanical standardization of semiconductor devices
Part 6-10: General rules for the preparation of outline drawings of surface mounted semiconductor device packages –
Dimensions of P-VSON
(IEC 60191-6-10:2003)

Normalisation mécanique des dispositifs
à semiconducteurs
Partie 6-10: Règles générales pour
la préparation des dessins
d'encombrement des dispositifs
à semiconducteurs pour montage
en surface –
Dimensions des boîtiers P-VSON
(CEI 60191-6-10:2003)

Mechanische Normung von
Halbleiterbauelementen
Teil 6-10: Allgemeine Regeln für
die Erstellung von Gehäusezeichnungen
von SMD-Halbleitergehäusen -
P-VSON Gehäusemaße
(IEC 60191-6-10:2003)

This European Standard was approved by CENELEC on 2003-11-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Lithuania, Luxembourg, Malta, Netherlands, Norway, Portugal, Slovakia, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47D/551/FDIS, future edition 1 of IEC 60191-6-10, prepared by SC 47D, Mechanical standardization of semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-10 on 2003-11-01.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2004-08-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2006-11-01

Annexes designated "normative" are part of the body of the standard. In this standard, annex ZA is normative. Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60191-6-10:2003 was approved by CENELEC as a European Standard without any modification.

Annex ZA
(normative)

**Normative references to international publications
with their corresponding European publications**

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191	Series	Mechanical standardization of semiconductor devices	EN 60191	Series
ISO/DIS 2692	-	Geometrical Product Specification - Geometrical tolerancing - Maximum material requirement (MMR) and least material requirement (LMR)	-	-

INTERNATIONAL STANDARD

IEC
60191-6-10

First edition
2003-11

Mechanical standardization of semiconductor devices –

Part 6-10:

**General rules for the preparation of outline drawings of
surface mounted semiconductor device packages –
Dimensions of P-VSON**

Normalisation mécanique des dispositifs à semiconducteurs –

Partie 6-10:

*Règles générales pour la préparation des dessins
d'encombrement des dispositifs à semiconducteurs
pour montage en surface –
Dimensions des boîtiers P-VSON*



Reference number
IEC 60191-6-10:2003(E)

Publication numbering

As from 1 January 1997 all IEC publications are issued with a designation in the 60000 series. For example, IEC 34-1 is now referred to as IEC 60034-1.

Consolidated editions

The IEC is now publishing consolidated versions of its publications. For example, edition numbers 1.0, 1.1 and 1.2 refer, respectively, to the base publication, the base publication incorporating amendment 1 and the base publication incorporating amendments 1 and 2.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**MECHANICAL STANDARDIZATION
OF SEMICONDUCTOR DEVICES –**

**Part 6-10: General rules for the preparation of outline drawings of
surface mounted semiconductor device packages –
Dimensions of P-VSON**

FOREWORD

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International Standard IEC 60191-6-10 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/551/FDIS	47D565/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until 2005. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-10: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Dimensions of P-VSON

1 Scope

This part of IEC 60191 provides the common outline drawings and dimensions for all types of structures and composed materials of plastic very thin small outline non-lead package (hereinafter called P-VSON).

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191(all parts), *Mechanical standardization of semiconductor devices*

ISO/DIS 2692: *Geometrical Product Specification (GPS) – Geometrical tolerancing – Maximum material requirement (MMR) and least material requirement (LMR)*.